HD Communications Corp.

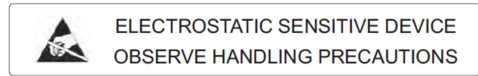
P/N : HD34391
MEMS BAND PASS FILTER

Features:

- Pass Band : 8.6G~ 10.0GHz
- Insertion Loss : 3.0dB
- Size : 13.65x5.0x0.5mm

Absolute Maximum Ratings

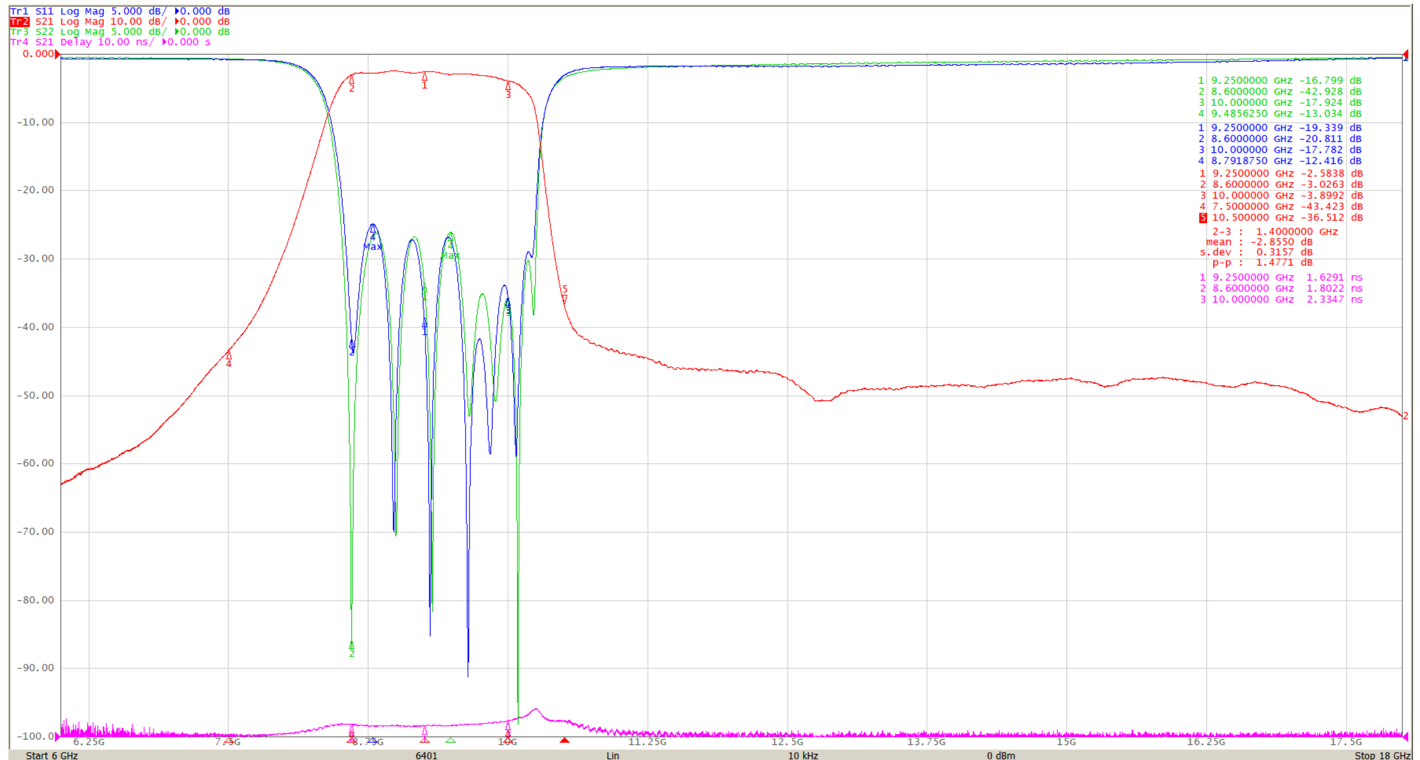
- Max. Input Power : +35dBm
- Storage Temperature : -55 ~ +85Deg.C
- Operating Temperature : -55 ~ +125Deg.C



Electrical Specifications (T_A=+25Deg.C, 50Ω system)

Parameter		Min.Value	Typical Value	Max.Value	Unit
Frequency Range		8.6 ~ 10.0			GHz
Insertion Loss (Fc)			2.58	3.0	dB
Ripple			1.47	2.0	dB
Attenuation	DC~@7.5GHz	40	43.42	-	dB
	@10.5GHz	30	36.51	-	dB
Return Loss		12.0	12.41	-	dB
Group Delay			2.31	4.0	ns

Test Curve



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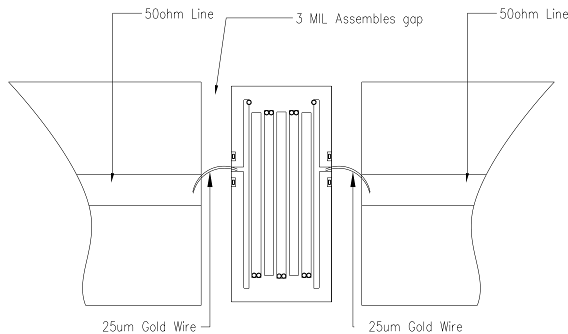
Size

Remarks:Unit : mm, Tolerance : ±0.25mm
1. Chip bottom is gold plated and grounded.
2. Bonding pressure points are gold plated.
3. Don`t bond on the through holes.

Applications

1. Assembly and Bonding Diagram. (Reference)



Assembly Diagram

2. The chip is back-metalized and can be die mounted with AuSn eutectic performs or with electrically conductive epoxy (for example ME8456).

3. The die should be assembled on carriers like Kovar or Mu-Cu which have same Coefficient of thermal expansion. (2.9ppm/℃) with Silicon, thickness 0.2mm max.

4. Handle the chips in a clean environment. DO NOT attempt to clean the chip using liquid cleaning systems.

5. Handle the chip along the edges with a vacuum collet or with a sharp pair of bent tweezers.